

ADMETA Plus 2015 - Poster Presentation list

#	Name	Affiliation	E-mail	Title
1	Daisuke Yamane	Tokyo Institute of Technology	yamane.d.aa@m.titech.ac.jp	A Study on Mechanical Structure of a MEMS Accelerometer Fabricated by Multi-layer Metal Technology
2	Yoriko Mizushima	Tokyo Institute of Technology	mizushima.y.aa@m.titech.ac.jp	Behavior of Copper Contamination for Ultra-Thinning of 300 nm Silicon Wafer down to <5um
3	Kotaro Sato	Tohoku University	koutarou.satou.p5@dc.tohoku.ac.jp	Grain growth and resistivity reduction of reflowed Cu - Mn in SiOC trench lines
4	Zuopeng He	Semiconductor manufacturing International Corporation	Zuopeng_he@smics.com	Low temperature dielectric oxide process study for TSV WLP application
5	Md. Rasadujaman	University of Yamanashi	rasadphy@duet.ac.bd	Copper Thin Film Growth using Cu(I) Amidinate Precursor in Supercritical Carbon Dioxide: Deposition Kinetics and
6	Eungrim Lee	Tohoku University	b4tm5304@s.tohoku.ac.jp	Electrical Contact Property and Interfacial Reaction of Mo on surface-treated InGaAs
7	Daisaku YANO	ORGANO Corporation	yano-d@organo.co.jp	Inhibition of Copper Corrosion by Removal of Hydrogen Peroxide and Dissolved Oxygen from Rinse Water using a
8	Soichiro Suzuki	Osaka Prefecture University	ssuzuki@chemeng.osakafu-u.ac.jp	Thermal stability of titanium carbide/nitride wiring resistance for p-type diamond contact material
9	Mitsuhiko Watanabe	University of Yamanashi	mitsuhirou@yamanashi.ac.jp	Versatility of ZnO as a room-temperature adhesion promoter for Cu/glass stacks
10	Naoto Noda	Air Liquide Laboratories	naoto.noda@airliquide.com	The study of precursor effect on low temperature PEALD SiN
11	Osamu Nakatsuka	Nagoya University	nakatuka@alice.xtal.nagoya-u.ac.jp	Crystalline Structure and Chemical Reaction of Ti Thin Layer
12	Yoko Takada	Osaka Prefecture University	ytakada@chemeng.osakafu-u.ac.jp	Ferroelectric properties of (Pb,Lu)Zr,TiO3 capacitors using AlZnO top electrodes pulsed laser deposited with different
13	Panart Khajornrungrat	Kyushu Institute of Technology	panart@mse.kyutech.ac.jp	Determination of Individual Sub 100 nm Nano-Particle Size in an Evanescent Field using Scattering Light Intensity
14	Dong-Yurl Yu	KITECH	Cwlee@kitech.re.kr	Joint Reliability of Sn-Cu-Cr for Automotive Electronics Modules
15	Changhong Hyun	SNU Precision Co., Ltd.	milho9@snuprecision.com	Critical dimension measurement of TSVs using WLSI
16	Sunho Kim	Sungkyunkwan Univ.	sunhofy@skku.edu	Performance enhancement for Ag nanowire-based transparent conductor using TiO2.Cs sol-gel
17	Sekwon Na	Sungkyunkwan Univ.	nase@skku.edu	The Mo alloying effects on microstructures and electrical properties for Yb silicidation
18	Ho yong	Sungkyunkwan Univ.	srntldh@skku.edu	Contact resistance between thermoelectric material and electrodes
19	Jeong-Gyu Song	Yonsei University	mussmi@yonsei.ac.kr	Low temperature silicon oxide process study for TSV WLP application
20	So-Yeon Lee	KIST	so.yeon_e@naver.com	Fabrication of Mechanically-robust Cu Films on Flexible Substrates Using Electron beam Irradiation
21	Daekyun Jeong	Kookmin University	trnstony@kookmin.ac.kr	Reduction on Sidewall Stress of Cu TSV with Lbl. Multilayers
22	Jae-Hak Lee	KIMM	jaehak76@kimm.re.kr	Micro Insert Bump Thermo-Compression Bonding for Multi-Chip Package
23	Byoung-Jun Cho	Hanyang University	bjcho303@nate.com	Effect of pH and Polisher's Conditions on Cu-BTA Complex Formation during Cu CMP Application
24	Jin-Woo Park	Yonsei University	lpark09@yonsei.ac.kr	The Applications of the Patterend Ag-nanowire Networks to Transparent Thin Film Heaters and Electrodes for Organic Light Emitting Diodes
25	Jongwan Jung	Sejong University		Growth of multilayer graphene by CVD and doping for graphene interconnect
26	Kukjoo Kim	UNIST, KIMM	zcartom@unist.ac.kr	Fabrication of High-resolution Bridge-like 3D Interconnects using Electrohydrodynamic Inkjet Printing
27	Chon-Hsin Lin	Asia-Pacific Institute of Creativity	cdlin@ms.apic.edu.tw	New copper-alloy film for industrial applications
28	Myungwoo Son	GIST	mwson@gist.ac.kr	Cu/graphene heterostructures for advanced interconnects: direct growth of graphene on Cu interconnects
29	Yonghyun Won	Seoul National Univ. Sci. and Tech.	eunkyung@seoultech.ac.kr	On-Chip Liquid Cooling Solution for High Power IC Devices
30	Jae-Oh Bang	Sungkyunkwan Univ.	bjaeoh@skku.edu	Thermo-mechanical Behavior of Die Attach Film on PCB Substrates for Multi-chip Packages
31	Min Young Lee	Yeungnam University	tmv177@naver.com	Atomic layer deposition of Ru thin films using new zero valent Ru precursors and molecular O2 and Application to
32	Byeonghyeon Jang	Yeungnam University	jangbh131@naver.com	A Study on the Characteristics of Al2O3 Films Deposited by Atomic Layer Deposition using a New Metallorganic
33	Younhwan Shin	Seoul National Univ. Sci. and Tech.	sdkim@seoultech.ac.kr	Experiment and Thermal Simulation of Cu Through Silicon Via in 3D IC
34	Youngju Nam	Seoul National Univ. Sci. and Tech.	sdkim@seoultech.ac.kr	Effects of Forming Gas/Plasma Treatment on Low Temperature Cu-Cu Direct Bonding
35	Gyu-Tae Park	Andong National University		Ni Barrier Effect on Electromigration Failure Mechanism of Cu/SnAg Microbump
36	Hyeonchul Lee	Andong National University	mserkat718@gmail.com	Effects of Post-Annealing and Temperature/Humidity Treatments on the Interfacial Adhesion Energy of Cu/SiNx
37	Jae-Chan Lee	Seoul National Univ.	odysseii@gmail.com	Enhancement of Electron mobility in Solution-Processed Indium Oxide Thin Films through W Doping
38	Seung-Min Lim	Seoul National Univ.	smsophia@snu.ac.kr	Modulation of Oxygen Vacancy and Stoichiometry in Amorphous Metal Oxides at Metal/Oxide Interfaces for
39	Kyung-Tae Jang	Seoul National Univ.	meetiyoung@snu.ac.kr	Structural effects on electromigration reliability under DC stressing for memory Devices
40	Min-Woo Jeong	Seoul National Univ.	zzthkdn91@snu.ac.kr	Composition Effects on Electrical Properties of Sputtered Bi-Te
41	Se-Hoon Park	KETI	psih104@keti.re.kr	Via interface modification of embedded chip resistor packages and its effect on drop shock reliability
42	Won Jae YEO	YEST	wjyeo@yest.co.kr	Development of wedge error compensation tool for chip to wafer package
43	JongHa Choi	Seoul Techno Park	lchoi@seoultp.or.kr	A Study on electrical properties of PDMS fine-pitch socket for testing BGA
44	Ji Hwan Kim	Seoul National Univ. Sci. and Tech.	malla2004@seoultech.ac.kr	Microstructural Investigation on Oxidation of Cu in Ag-coated Cu Film Using FB-TEM Technique
45	Taewook Nam	Yonsei University	tnam@yonsei.ac.kr	Atomic Layer Deposition of Cobalt-based bifunctional Layer or Cu Interconnect
46	Jun Yeob Song	KIMM	sjy658@kimm.re.kr	Step-covered interconnection on Flexible Electronic Devices by Using Electrohydrodynamic Jet Printing System
47	Y. Nagendra Prasad	Micro Chemical Korea Co. Ltd	nagmck@gmail.com	Material Removal Mechanism by Slurry Free Lapping Pad
48	정소현	SK Hynix		Via Filling 공법에 따른 TC 신뢰성 연구
49	최정열	SK Hynix		DRAM Package 구조 및 재료에 따른 warpage 거동에 관한 연구
50	김시한	SK Hynix		Thin Solar Cell Package의 휨 거동 연구
51	Junbeom Kim	Yeungnam University	dembj@ynu.ac.kr	Atomic Layer Deposition of F-free tungsten nitride thin films using NH3 plasma and N2/H2 mixture plasma